

Amendments to the Specification:

Kindly replace the paragraph beginning on page 7, line 5 with the following amended paragraph.

-- Referring to FIGURE 4, there is shown a cross-sectional view of a solder joint having an intermetallic region formed between solder 25 and the pad 10 pads 16 and 29. As generally occurs in a soldering operation, intermetallic regions are formed within both solder 25 and pads 16 and 29, and an intermetallic boundary 15 is boundaries 15' being formed therein shown. The pad 10 has pads 16, 29 both have substantially planar lower and upper surfaces, respectively. Upper and lower surfaces of pads 16 and 29, respectively, have the serpentine solder configuration depicted in FIGURE 3a. It will be observed that the respective micro-cracking 20 at near intermetallic boundary 15 is following boundaries 15' follow a circuitous or meandering path. The lengthening of the crack pathway increases the useful life of the solder joint. Other pad configurations are shown in FIGURES 3b through 3d. As before, this results is the case with the configuration of FIGURE 3a, theses other configurations result in micro-crack pathways that are interrupted, lengthened, or constrained. In a similar manner, these configurations are expected to increase fatigue life of the solder joint, as is that of the solder design shown in FIGURE 3a. --